

Grain Size Distribution

d ₁₀	< 20 μm
d ₅₀	~ 80 μm
d ₉₀	> 160 μm

Chemical Composition

Y ₂ O ₃	99,999 %
SiO ₂	< 0.001 %
Na ₂ O	< 0.043 %
Fe ₂ O ₃	< 0.005 %

These properties are typical but do not constitute specifications

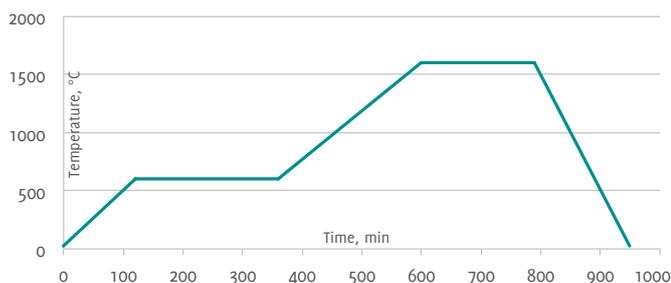
Physical Properties

Green Density ¹⁾	2.98 g/cm ³
Sintered Density ¹⁾	4.98 g/cm ³
Apparent Density	1.6 g/cm ³
Flexural Strength	—
Shrinkage	~ 20 %
Δm ²⁾	~ 13 %
Color	white

1) at 200 MPa 2) weight loss after sintering

Recommended Sintering Conditions

Sintering Temperature	1600 °C
Debinding	600 °C



The shown debinding and sintering cycles are exemplary. More information on request.

Applications

Semiconductor Applications, for Cold Isostatic Pressing, Green Machining, Parts with Complex Geometry

Advantages.

- Excellent powder flowability and pressing behavior for low variance of die filling and green density.
- High dimensional accuracy after sintering, low dimensional scrap rate.
- Improved binder system with non-sticking properties on die surface. Reduced down time for mold cleaning.
- Formulation with eco-friendly carbon precursor. No use of phenolic resin. Clean and safe debinding process without toxic emissions. Reduced deposits inside debinding equipment provide for reduced maintenance down time.
- Reduced pressure to obtain the required green density. Reduced cost factor related to tool wear.

